

## P-Ch 30V Fast Switching MOSFETs

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

## Product Summary



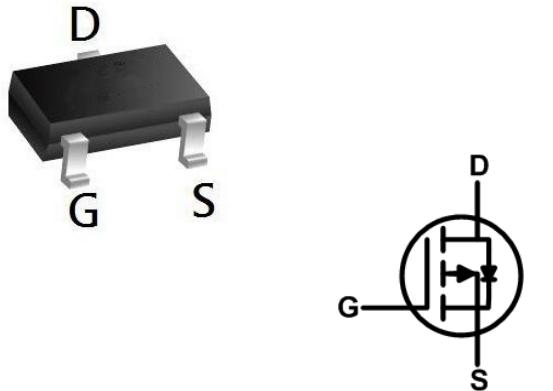
BVDSS	RDS(ON)	ID
-30V	14mΩ	-9.5A

## Description

The XR30P10L is the highest performance trench P-ch MOSFETs with extreme high cell density, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications .

The XR30P10L meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

## SOT23-3L Pin Configuration

Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		-30	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ\text{C}$	-9.5	A
		$T_A = 100^\circ\text{C}$	-5.5	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		-46	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>		35	mJ
$P_D$	Power Dissipation	$T_A = 25^\circ\text{C}$	3.0	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		48	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

## P-Ch 30V Fast Switching MOSFETs

Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-30	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}, V_{GS}=0\text{V},$	-	-	-1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{DS(\text{on})}$ Note3	Static Drain-Source on-Resistance	$V_{GS}=-10\text{V}, I_D=-5\text{A}$	-	14	20	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-5\text{A}$	-	19	27	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=-15\text{V}, V_{GS}=0\text{V}, f=1.0\text{MHz}$	-	1330	-	pF
$C_{oss}$	Output Capacitance		-	183	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	156	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=-15\text{V}, I_D=-5\text{A}, V_{GS}=-10\text{V}$	-	22	-	nC
$Q_{gs}$	Gate-Source Charge		-	1.0	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	1.8	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-15\text{V}, I_D=-10\text{A}, V_{GS}=-10\text{V}, R_{GEN}=2.5\Omega$	-	9	-	ns
$t_r$	Turn-on Rise Time		-	13	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	48	-	ns
$t_f$	Turn-off Fall Time		-	20	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current		-	-	-9.5	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-46	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}, I_s=-15\text{A}$	-	-0.8	-1.2	V
$t_{rr}$	Reverse Recovery Time	$T_J=25^\circ\text{C}, V_{DD}=-24\text{V}, I_F=-2.8\text{A}, dI/dt=-100\text{A}/\mu\text{s}$	-	64	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	25	-	nC

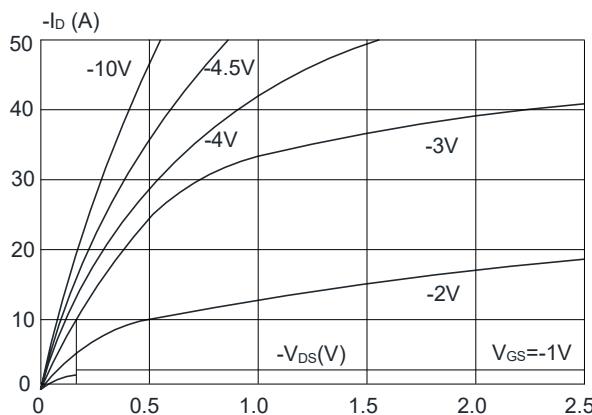
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition:  $T_J=25^\circ\text{C}, V_{GS}=10\text{V}, R_G=25\Omega, L=0.5\text{mH}, I_{AS}=-12.7\text{A}$

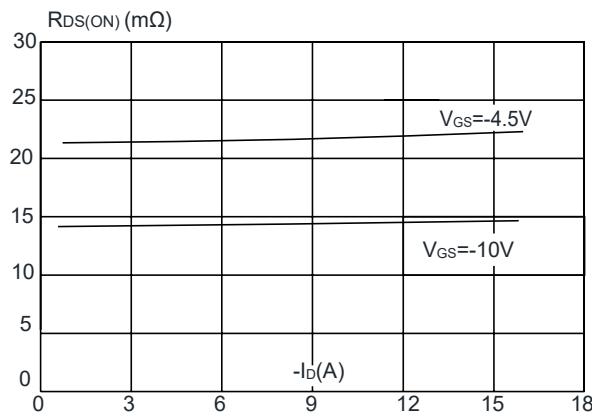
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$

## Typical Performance Characteristics

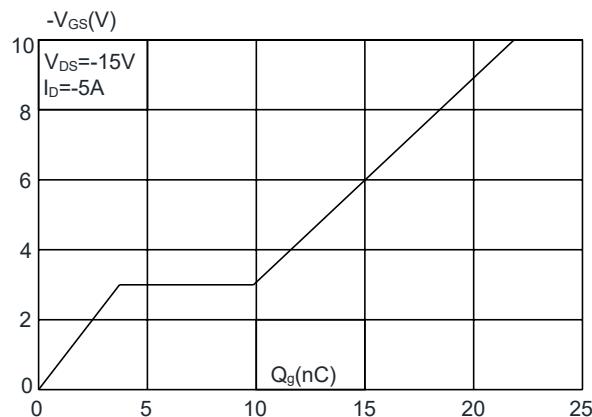
**Figure 1:** Output Characteristics



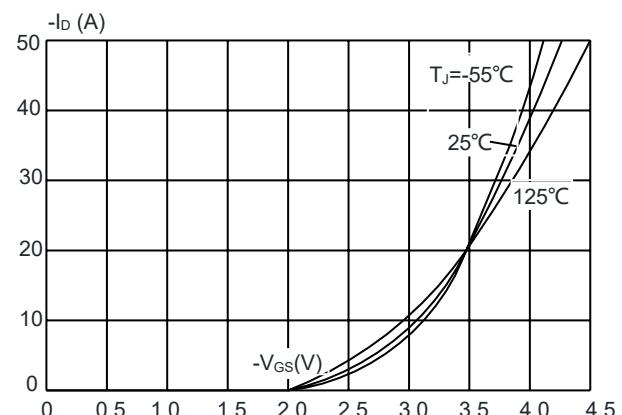
**Figure 3:** On-resistance vs. Drain Current



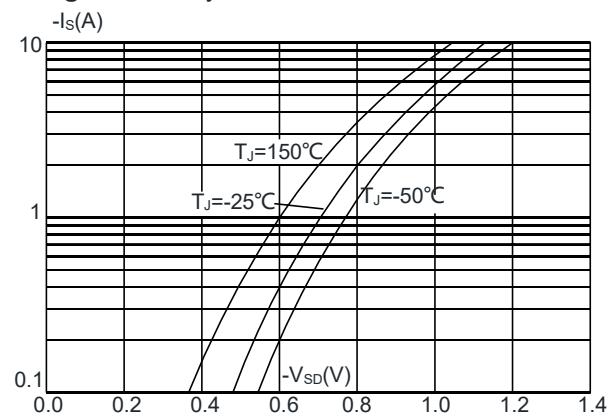
**Figure 5:** Gate Charge Characteristics



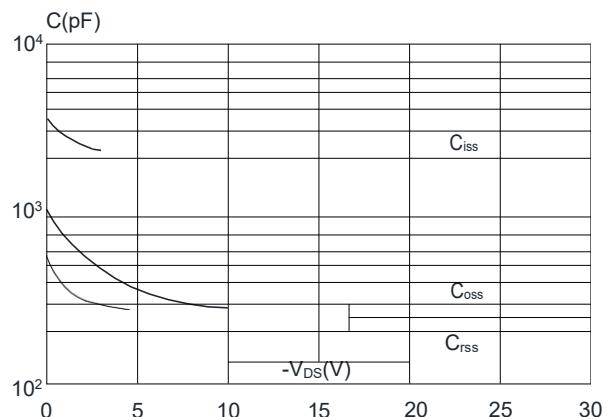
**Figure 2:** Typical Transfer Characteristics



**Figure 4:** Body Diode Characteristics

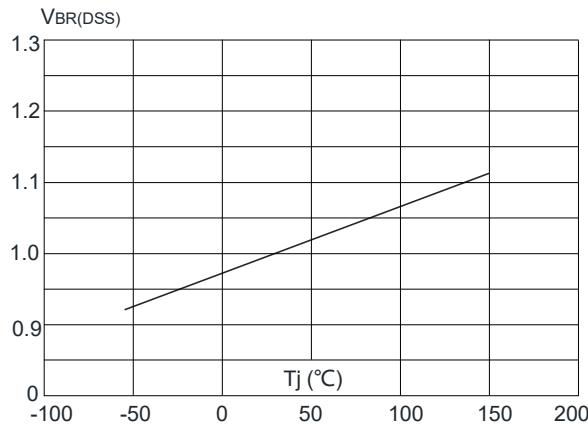


**Figure 6:** Capacitance Characteristics

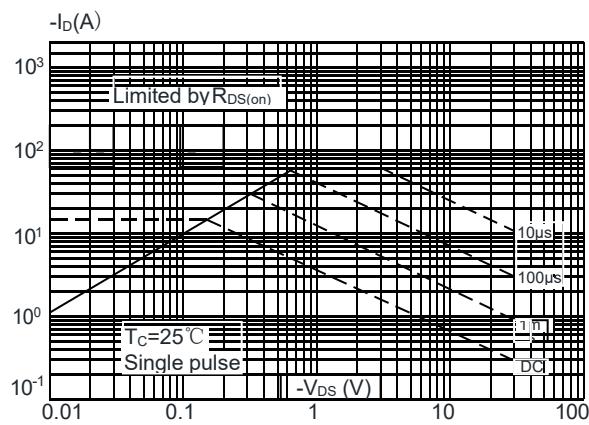


## P-Ch 30V Fast Switching MOSFETs

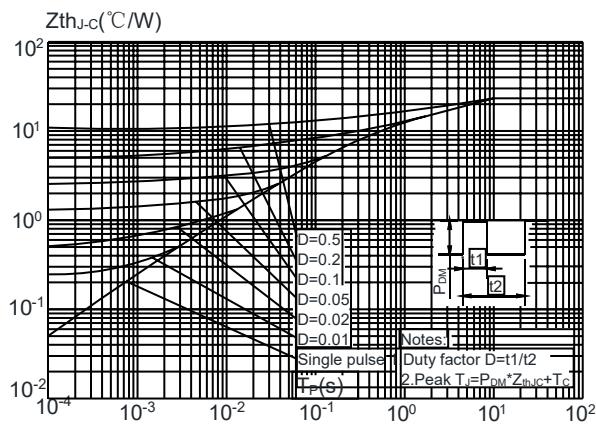
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



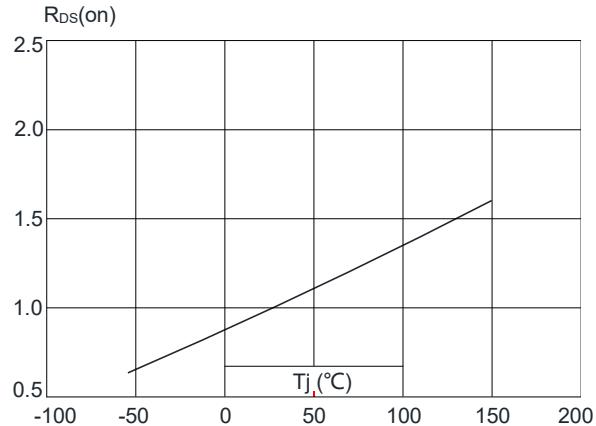
**Figure 9:** Maximum Safe Operating Area



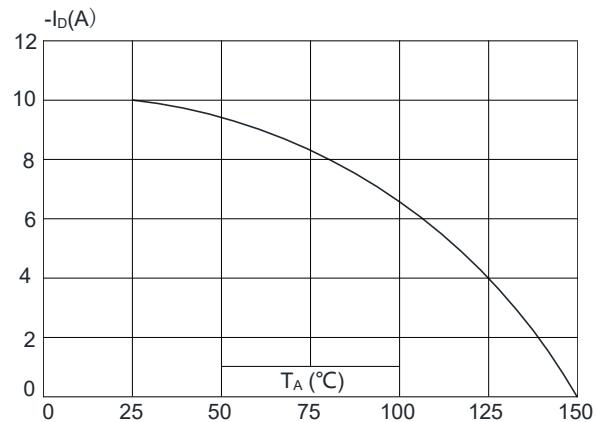
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Figure 8:** Normalized on Resistance vs. Junction Temperature



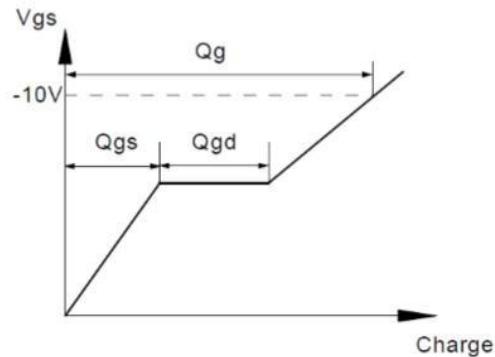
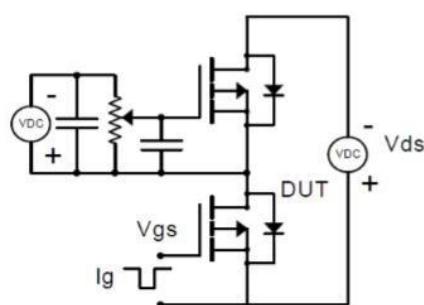
**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



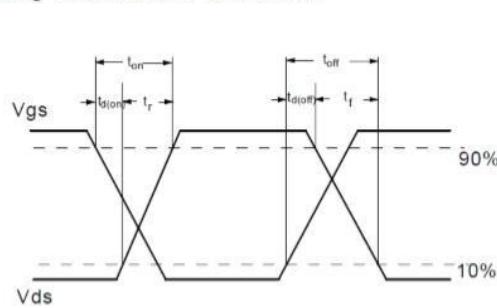
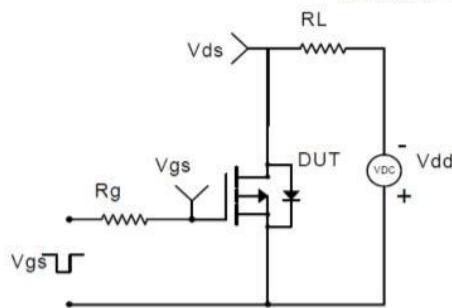
## P-Ch 30V Fast Switching MOSFETs

## Test Circuit

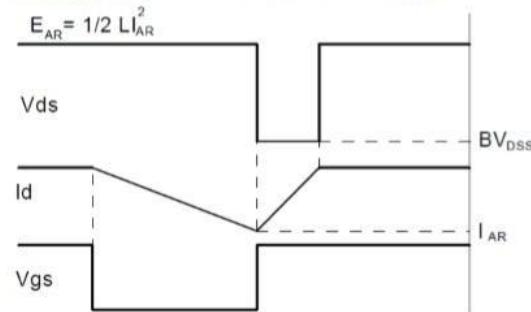
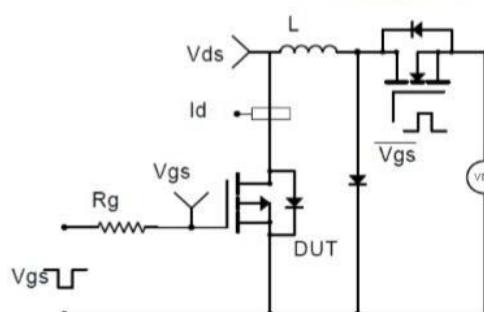
Gate Charge Test Circuit &amp; Waveform



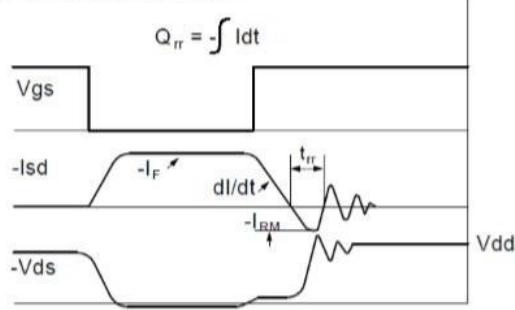
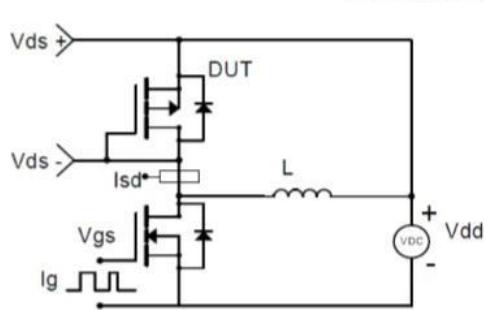
Resistive Switching Test Circuit &amp; Waveforms



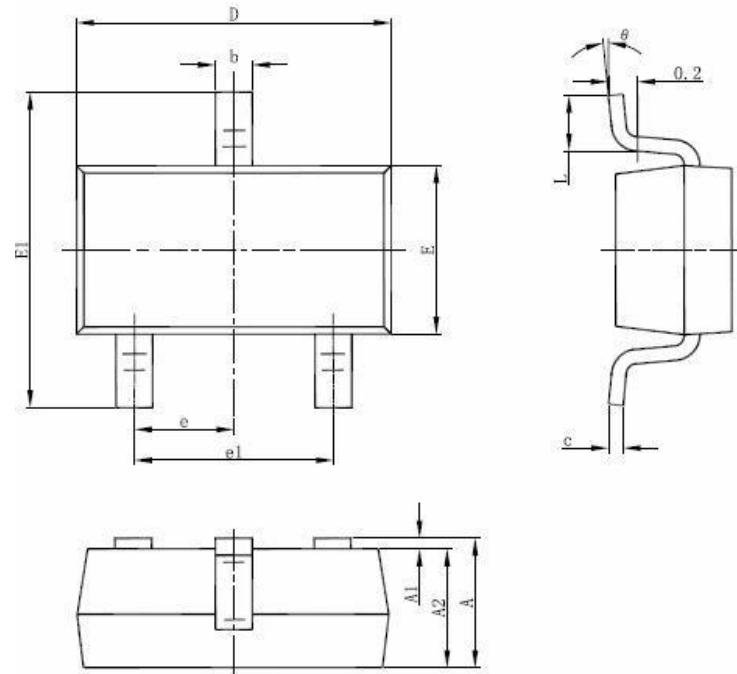
Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms



Diode Recovery Test Circuit &amp; Waveforms



## SOT-23-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°